

MCM'22 JULY 31, 2022 - AUGUST 2, 2022 | PRAGUE, CZECH REPUBLIC

8TH WORLD CONGRESS ON MECHANICAL, CHEMICAL, AND MATERIAL ENGINEERING

MCM'22 is composed of 4 conferences, while each conference consists of an individual and separate theme, they share considerable overlap, which prompted the organization of this congress.

The goal of this undertaking is to bring together experts in each of the specialized fields, and at the same time allow for cross pollinations and sharing of ideas from the other closely related research areas. Interested authors, researchers, and industrial experts are invited to register for the conference that best resonates with their technical background. At the same time, attendees are permitted, and even encouraged, to attend talks from co-located conferences.



PAPER SUBMISSION DEADLINE: JANUARY 7, 2022

EARLY-BIRD REGISTRATION: APRIL 22, 2022

HTFF
2022

**9th International Conference on
Heat Transfer and Fluid Flow
(HTFF'22)**

www.htffconference.com

ICMIE
2022

**11th International Conference on
Mechanics and Industrial Engineering
(ICMIE'22)**

www.icmie.net

MMME
2022

**9th International Conference on Mining,
Material, and Metallurgical Engineering
(MMME'22)**

www.mmmeconference.com

ICCPE
2022

**8th International Conference on
Chemical and Polymer Engineering
(ICCPE'22)**

www.cpeconference.com

The proceedings of this congress will be indexed by

Scopus and Google Scholar.

SUBMISSIONS

Submissions in the form of extended abstracts, short papers, and full manuscripts are welcome. All submitted papers will be peer reviewed. All accepted and presented papers will be published in the conference proceedings, under an ISBN reference in a USB drive. The online version of the proceedings will also be published under an ISSN reference and each paper in the proceedings will be assigned unique **DOIs by Crossref**. The proceedings will be permanently archived in **Portico** (one of the largest community-supported digital archives in the world).

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Dr. Huihe Qiu
The Hong Kong
University of Science & Technology
Congress Chair



Dr. Yuwen Zhang
University of Missouri, USA
Congress Co-Chair



INTERNATIONAL
ASET



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Dr. Frank Cheng

University of Calgary, Canada
MMME'22 Keynote Speaker



Dr. Xinwei Wang

Iowa State University, USA
HTFF'22 Keynote Speaker



Dr. Sylvie Lorente

Villanova University, USA
HTFF'22 Keynote Speaker

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